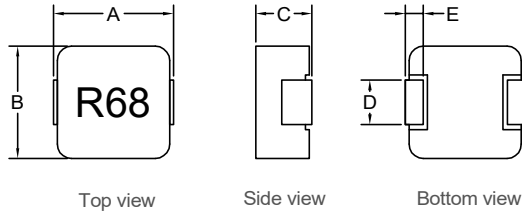


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Outline Dimensions(Unit:mm)



A	B	C	D	E
±0.50	±0.30	±0.20	REF	REF
11.5	10.0	3.80	3.00	2.00

List of UL Certificate:

Part Name	Material	Specification	Supplier	UL
Core	Carbonyl material			
Wire	Enamelled copper wire			

Electronical Schematic

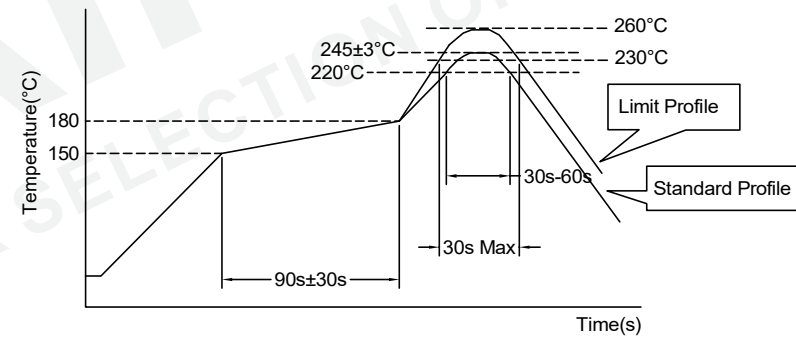


Suggested Pad layout



H	4.10 REF
I	4.10 REF
J	5.40 REF

Recommended Soldering Temperature Graph.



Electrical Characteristics(@25°C)

Inductance 100KHz,1V	DC Resistor	Isat (A)	Irms (A) ΔT≤40°C
0.68uH±20%	2.10mΩ Max	L(43.0A)≥70%*LOA	22.0A

- \*\*\*Operating Temperature: -40°C~+125°C (Including temperature rise)
- \*\*\*Storage Temperature: -40°C~+125°C
- \*\*\*Storage Humidity:RH10%~70%.
- \*\*\*Weight:Approximately 2.38g.

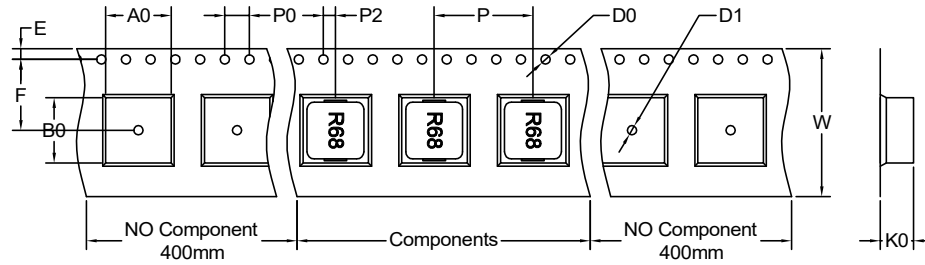
	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

				Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX: +86-550-7831133	 Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Make: Qiumei.Liu Checked: Beson. zhan Approved: Anson. zhan	<b>DRAWING TITLE</b> CARBONYL MATERIAL SMD POWER INDUCTORS Material Number: A341040XS330	Customer Name: Document/Rev: 00 Specification Sheet: 1 of 4 Date of Recognition: Jan./02/2020
REV	DESCRIPTION	APPD	DATE					

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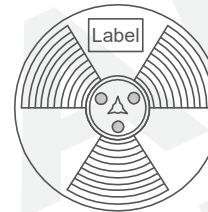
Packing Specifications(Unit:mm):



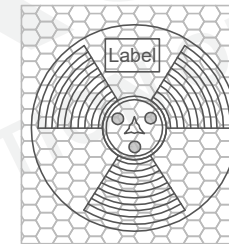
A0	10.5	F	11.5
B0	11.3	D0	1.50
P	16.0	D1	1.50
P0	4.00	K0	4.50
P2	2.00	W	24.0
E	1.75		



Quantity:500pcs/Reel



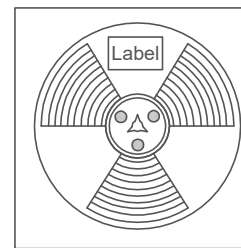
Quantity: 500pcs



PE bag



Outer cases: 3000pcs/box  
Insufficient boxes filled with inner boxes or fillers



Inner box  
Quantity: 1500 pcs/box

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Unit of measurement: mm

Make: Qiumei.Liu  
Checked: Beson. zhan  
Approved: Anson. zhan

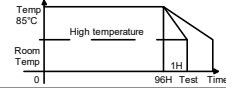
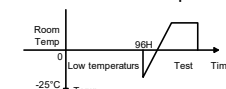
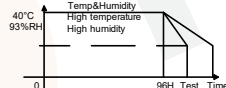
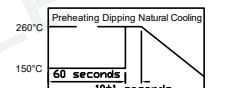
**DRAWING TITLE**  
CARBONYL MATERIAL  
SMD POWER INDUCTORS  
Material Number: A341040XS330

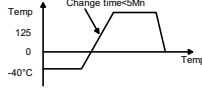
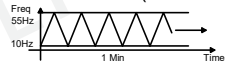
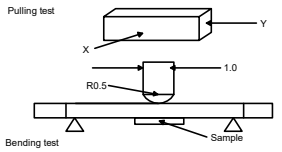
Customer Name:  
Document/Rev: 00  
Specification Sheet: 2 of 4  
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Reliability Testing:

Ltem	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $85 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Temperature: $25 \pm 2^\circ\text{C}$ Time: $96 \pm 2$ hours.  Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	1.Dry oven at a temperature of $40^\circ \pm 5^\circ\text{C}$ for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature: $40 \pm 2^\circ\text{C}$ , Humidity: $93 \pm 3\% \text{RH}$ Time: $96 \pm 2$ hours. 4.Tested while the specimens are still in the chamber. 5. Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Preheat: $150^\circ\text{C}$ ,60 second. Solder:Sn/Ag/Cu. Solder:Temperature: $260 \pm 5^\circ\text{C}$ . Flux:Rosin flux. Reflow peak time 10 second at $260^\circ\text{C}$ 

Ltem	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	First- $40^\circ\text{C}$ for T time,next+ $125^\circ\text{C}$ Ttime as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for 5 second. Soler:Sn(93.5)Ag(3.5). Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ .	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ . 3. $\Delta Q/Q \leq 30\%$ . 4. $\Delta DCR/DCR \leq 10\%$ . For T:weiges $\leq 28\text{g}$ :15 Min 28g $\geq$ weights $\leq 136\text{g}$ :30 Min	Packaged & Drop down from 1m with $981\text{m/s}^2$ (100G)attitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal $A \leq 8(\text{Sq M})$ $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 5\text{N}$ time:30sec Force $\geq 10\text{N}$ time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

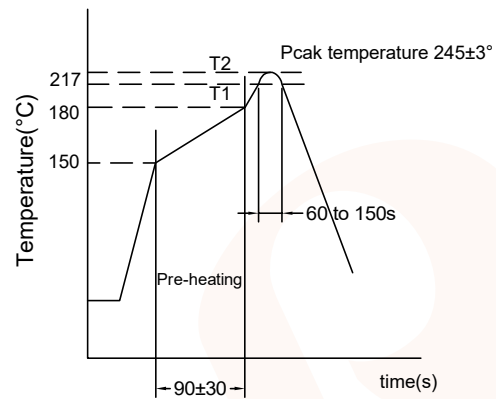
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								Document/Rev: 00 Specification Sheet: 3 of 4 Date of Recognition: Jan./02/2020

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Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last, to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar, smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



Use rosin-based flux  
Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).  
Use lead-free solder, use Sn-3.0Ag-0.5Cu solder  
Standard thickness of solder paste: 0.12-0.15mm

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REV	DESCRIPTION	APPD	DATE					